

SLD60R280E7

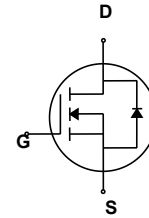
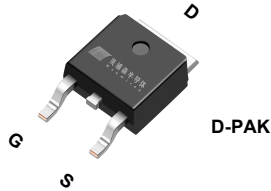
600V N-Channel Multi-EPI Super-JMOSFET

General Description

This Power MOSFET is produced using Msemitek's advanced Superjunction MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies.

Features

- 15A, 600V, $R_{DS(on)typ} = 0.28\Omega @ V_{GS} = 10V$
- Low gate charge (typical 19.6nC)
- High ruggedness
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	SLD60R280E7	Units
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$) - Continuous ($T_C = 100^\circ\text{C}$)	15	A
		8	A
I_{DM}	Drain Current - Pulsed (Note 1)	37.5	A
V_{GSS}	Gate-Source Voltage	± 30	V
EAS	Single Pulsed Avalanche Energy (Note 2)	711	mJ
I_{AR}	Avalanche Current (Note 1)	3.0	A
E_{AR}	Repetitive Avalanche Energy	1.11	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	20	V/ns
	MOSFET dv/dt	100	
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$) - Derate above 25°C	111	W
		0.88	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

* Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	SLD60R280E7	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.13	$^\circ\text{C}/\text{W}$
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^\circ\text{C}/\text{W}$

Package Marking

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
SLD60R280E7	SLD60R280E7	TO-252	Tape&Reel	2500	25000

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ mA}$	600	--	--	V
		$V_{GS} = 0\text{ V}, I_D = 0.25\text{ uA}, T_J = 150^\circ\text{C}$	600	--	--	
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	uA
		$V_{DS} = 480\text{ V}, T_C = 125^\circ\text{C}$	--	2	--	uA
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\text{ uA}$	2.5	--	4.5	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 7.5\text{ A}$	--	238	280	mΩ
R _G	Gate resistance	F=1MHZ	--	1.1	--	Ω

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V},$ $f = 1\text{ MHz}$	--	780	--	pF
C _{oss}	Output Capacitance		--	23	--	pF
C _{o(tr)}	Time Related Output Capacitance	$V_{DS} = 0\text{ V to } 400\text{ V}, V_{GS} = 0\text{ V}$	--	300	--	pF
C _{o(er)}	Energy Related Output Capacitance		--	37	--	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	$V_{DS} = 400\text{ V}, I_D = 5.3\text{ A}$ $V_{GS} = 10\text{ V}, R_G = 10\ \Omega$ See Figure 13	--	7.6	--	ns
t _r	Turn-On Rise Time		--	6.7	--	ns
t _{d(off)}	Turn-Off Delay Time		--	38.2	--	ns
t _f	Turn-Off Fall Time		--	8.4	--	ns
Q _g	Total Gate Charge	$V_{DS} = 400\text{ V}, I_D = 5.3\text{ A},$ $V_{GS} = 10\text{ V}$	--	19.6	--	nC
Q _{gs}	Gate-Source Charge		--	3.7	--	nC
Q _{gd}	Gate-Drain Charge		--	9.7	--	nC

Drain-Source Diode Characteristics and Maximum Ratings

I _S	Maximum Continuous Drain-Source Diode Forward Current	--	--	12.5	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	37.5	A	
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 5.3\text{ A}$	--	--	1.2	V
t _{rr}	Reverse Recovery Time	$V_{DD} = 400\text{ V}, I_S = 5.3\text{ A},$ $di_F / dt = 100\text{ A/us}$	--	234	--	ns
Q _{rr}	Reverse Recovery Charge		--	2.2	--	uC

※Notes:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. $L=79\text{ mH}, I_{AS} = 3\text{ A}, R_G = 25\ \Omega$, starting $T_J = 25^\circ\text{C}$.
3. $I_{SD} \leq 5.3\text{ A}, di/dt \leq 100\text{ A/us}, V_{DD} \leq 400\text{ V}$, starting $T_J = 25^\circ\text{C}$.

Typical Characteristics

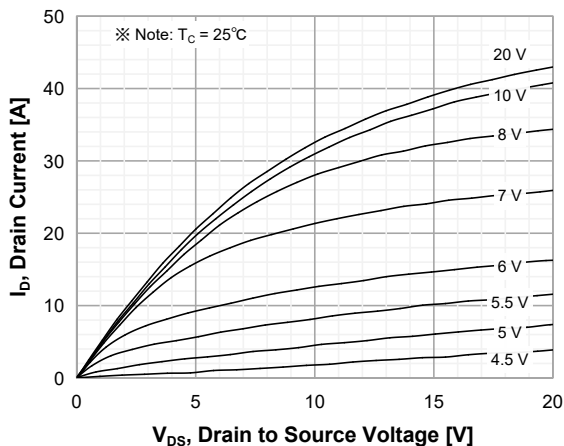


Figure 1. On-Region Characteristics

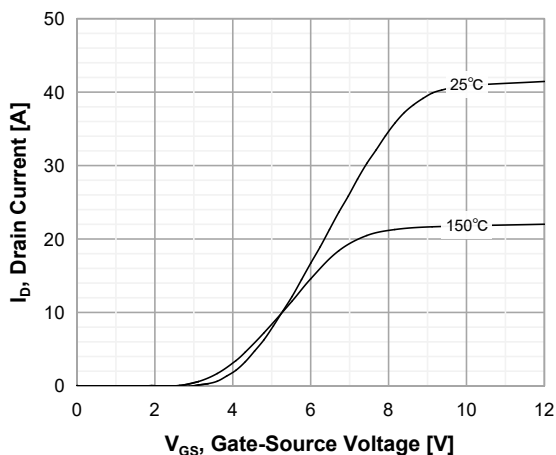


Figure 2. Transfer Characteristics

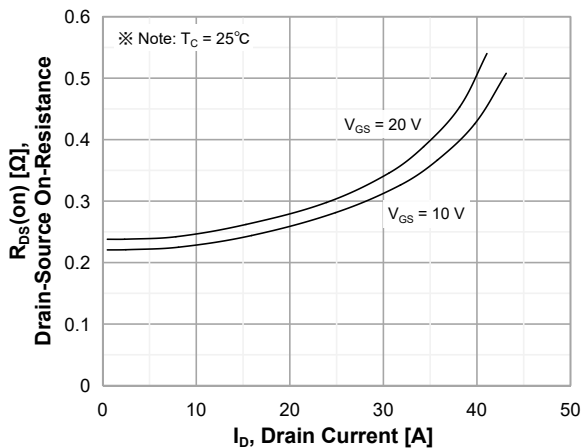


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

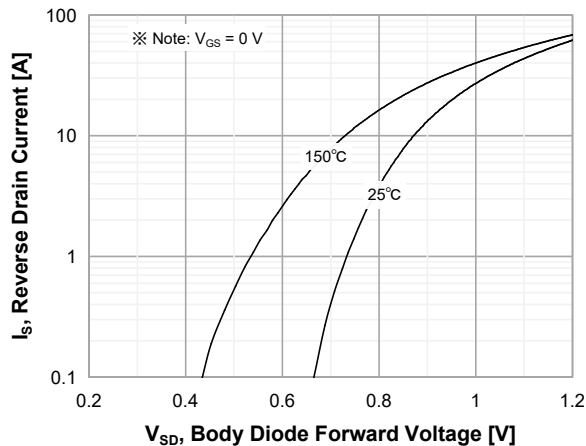


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

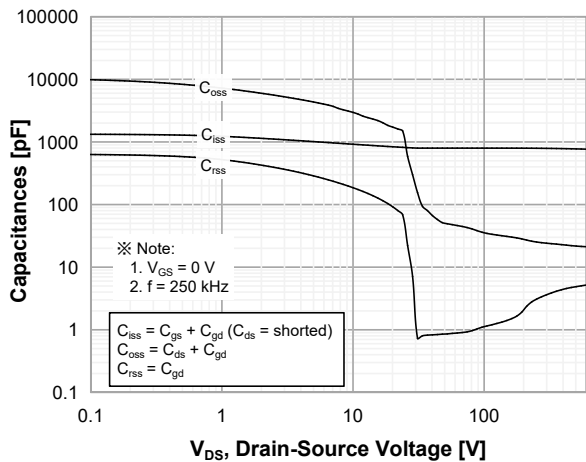


Figure 5. Capacitance Characteristics

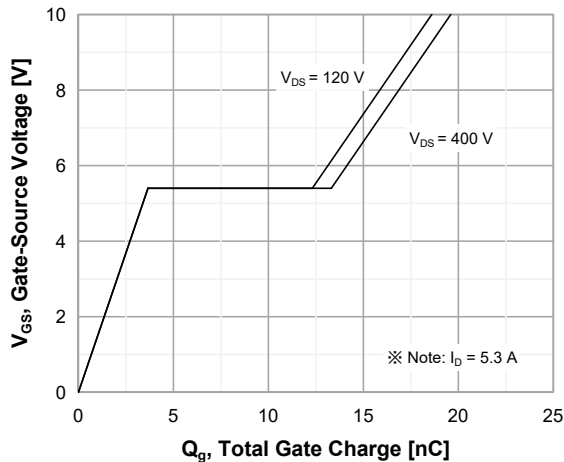


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

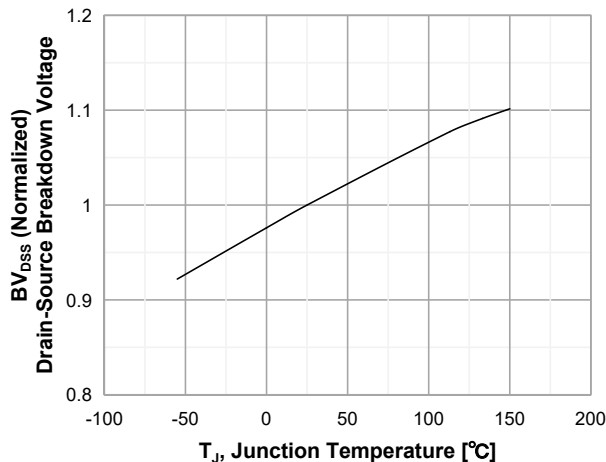


Figure 7. Breakdown Voltage Variation vs Temperature

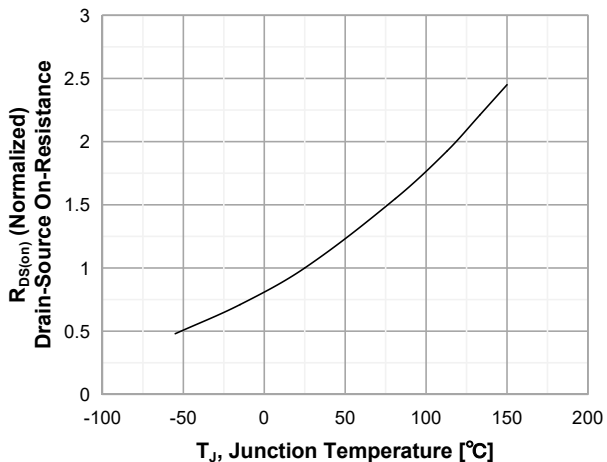


Figure 8. On-Resistance Variation vs Temperature

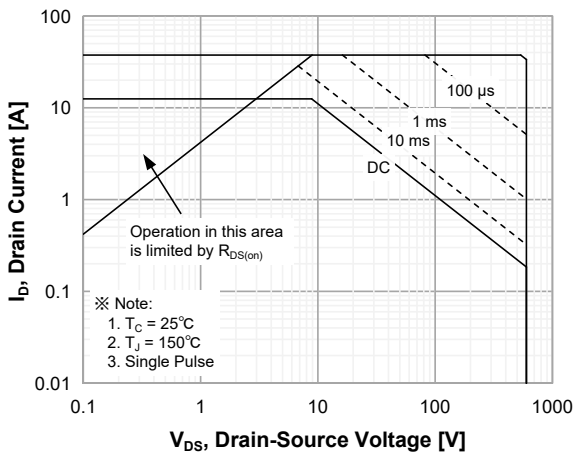


Figure 9. Maximum Safe Operating Area

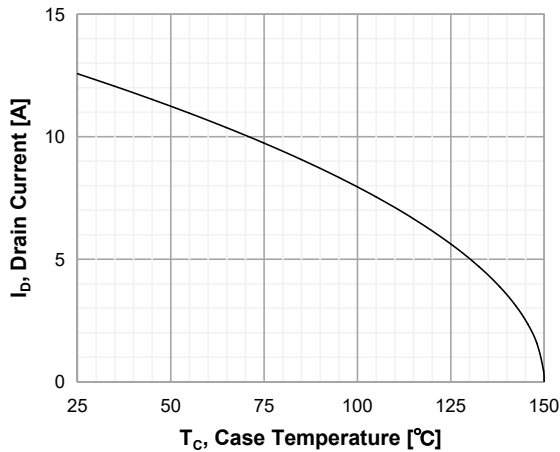


Figure 10. Maximum Drain Current vs Case Temperature

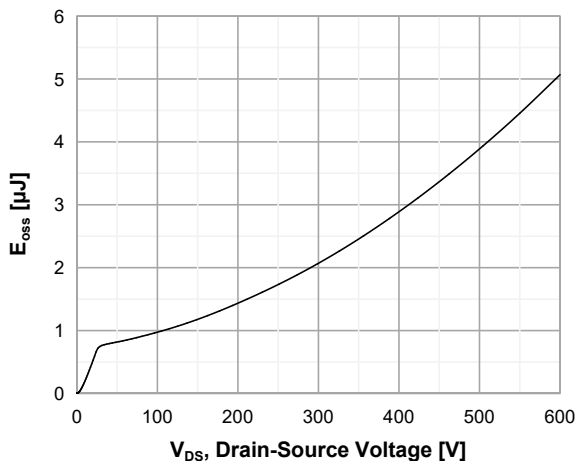


Figure 11. E_{OSS} vs. Drain to Source Voltage

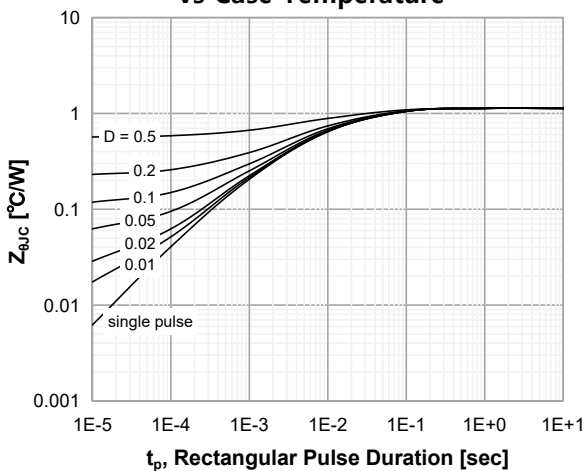
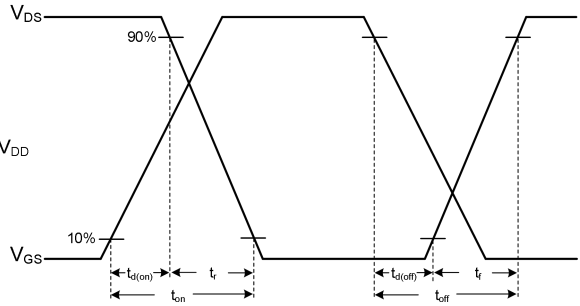
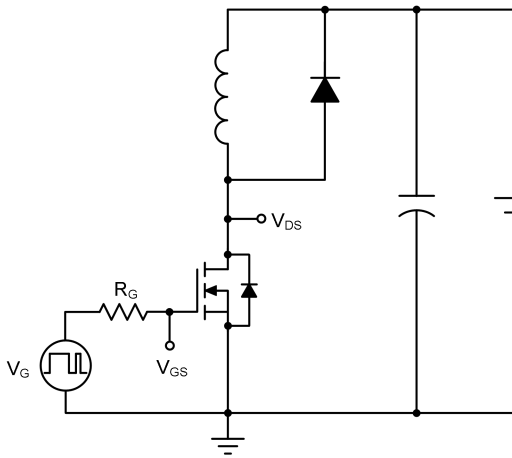
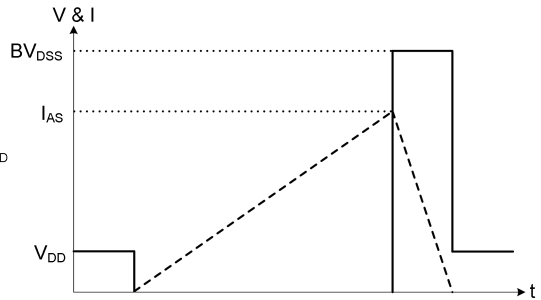
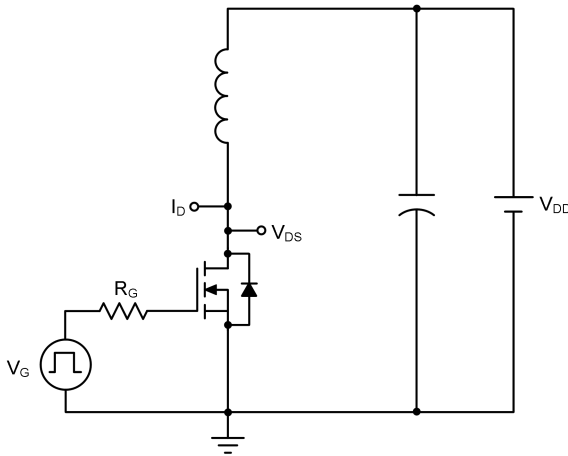


Figure 12. Transient Thermal Response Curve

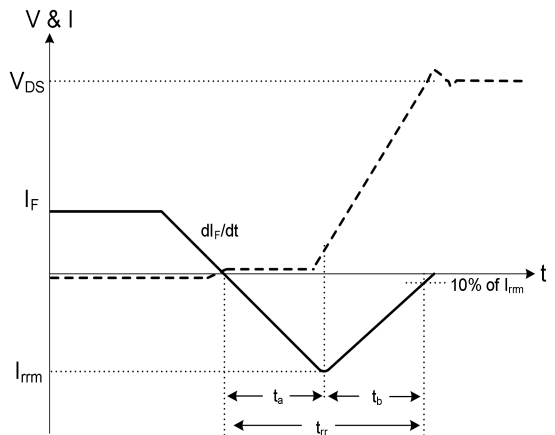
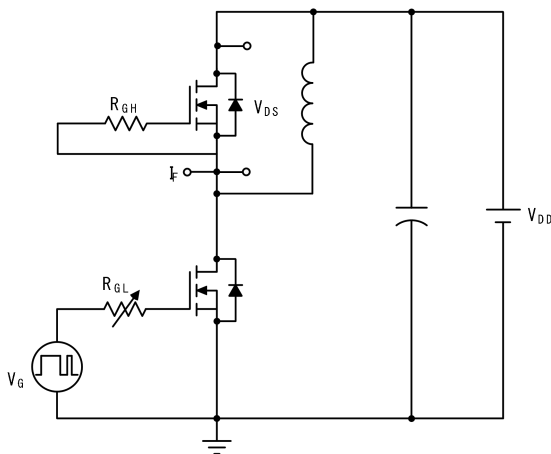
Inductive Load Switching Test Circuit and Waveforms



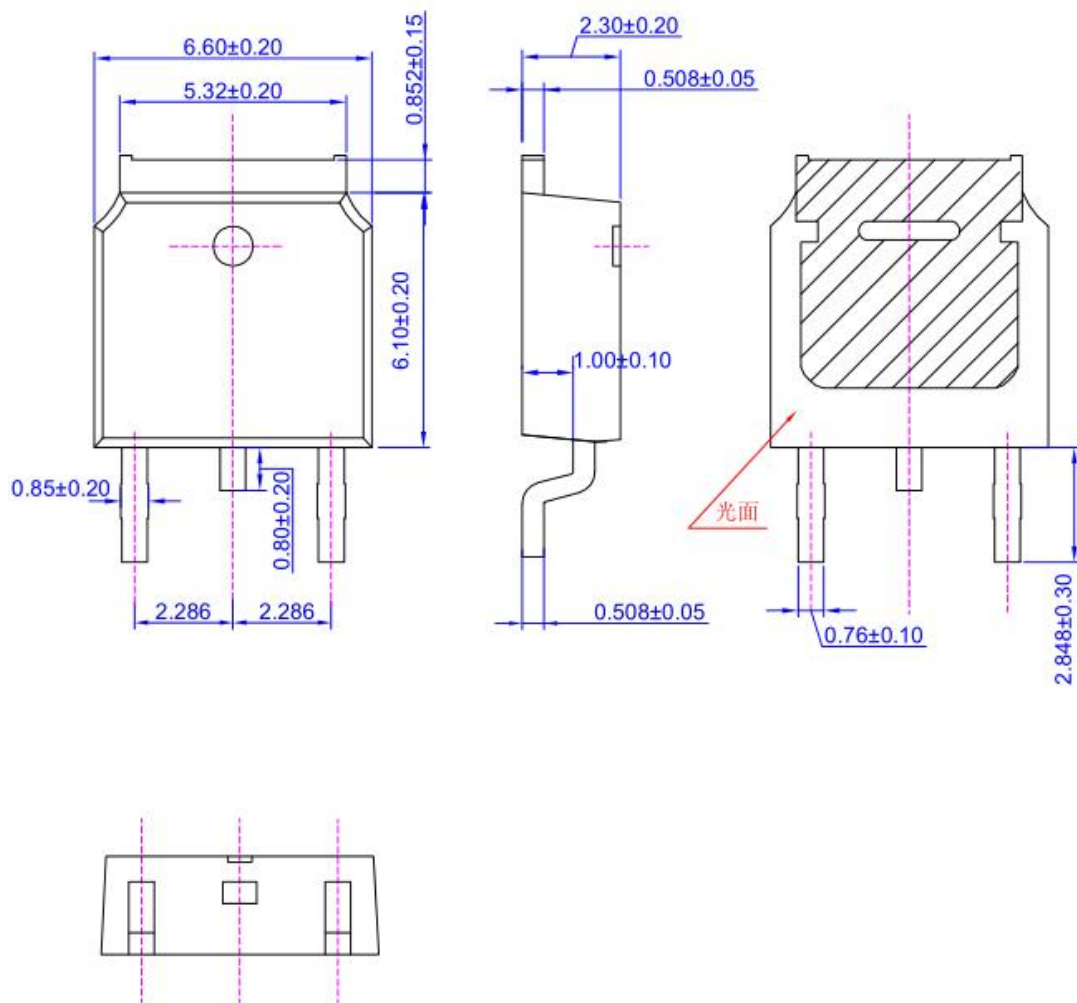
Unclamped Inductive Switching Test Circuit and Waveforms



Peak Diode Recovery dv/dt Test Circuit and Waveforms



TO-252 OUTLINE



NOTE:

- 1The plastic package is not marked as smooth surface $Ra=0.1$; Subglossy surface $Ra=0.8$
- 2.Undeclared tolerance ± 0.25 , Unmarked fillet $R_{max}=0.25$

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